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Application Number		Not Yet Assigned			
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First Named Inventor		Munehiro TADA			
Art Unit		Not Yet Assigned			
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Sheet	1	of	1		

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. <sup>1</sup>	Document Number		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document
		Number	Kind Code <sup>2</sup> (if known)		
		US 2003/0001282	A1	01-02-2003	Herman Meynen
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FOREIGN PATENT DOCUMENTS							
Examiner Initials*	Cite No. <sup>1</sup>	Foreign Patent Document			Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Translation <sup>6</sup>
		Country Code <sup>3</sup>	Number <sup>4</sup>	Kind Code <sup>5</sup> (if known)			
		JP	2000-183166	A	06-30-2000	NEC CORP.	
		WO	2001/054190	A1	07-26-2001	ADVANCED MICRO DEVICES	
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NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city, and/or country where published.	Translation <sup>6</sup>
		Tada, M., et al. "BARRIER-METAL-FREE (BMF), Cu DUAL-DAMASCENE INTERCONNECTS WITH Cu-epi-CONTACTS BURIED IN ANTI-DIFFUSIVE, LOW-k ORGANIC FILM," 2001 Symposium on VLSI Technology, June 12, 2001, pages 13-14.	
		Tada, M., et al. "A 65nm-NODE Cu INTERCONNECT TECHNOLOGY USING POROUS SiOCH FILM (K=2.5) COVERED WITH ULTRA-THIN, LOW-k PORE SEAL (k=2.7), International Electron Devices Meeting 2003 Technical Digest, December 8-10, 2003, pages 35.2.1 to 35.2.4.	

Examiner Signature	/Bac Au/	Date Considered	06/07/2008
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